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TITLE : MULTILAYER BOARD

ABSTRACT : PURPOSE: To prevent the peeling of a copper layer and the deformation of a board due to temperature change, and facilitate the recycling of resin, by arranging a resin plate made of liquid crystal polymer whose thermal expansion coefficient has a specified value and a copper layer or a copper alloy layer which are formed on the resin plate and have copper contents larger than or equal to a specified value.

CONSTITUTION: An oxygen-free copper foil (Cu: 99.99%, O<sub>2</sub>: 100ppm or less) of thickness 0.07mm, width 250mm and length 5000mm is bonded to a resin plate by using epoxy based adhesive agent, thereby forming a multilayer board. As the resin plate, a plate member of thickness 3mm, width 250mm and length 500mm is used which is composed of aromatic polyester being liquid crystal polymer. The thermal expansion coefficient of a conducting layer is  $17.0 \times 10^{-6}/^{\circ}\text{C}$ , and that of a resin board is  $16.2 \times 10^{-6}/^{\circ}\text{C}$ . Thereby the peeling of a copper layer and the deformation of a board can be prevented, and the recycling of resin is facilitated.

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